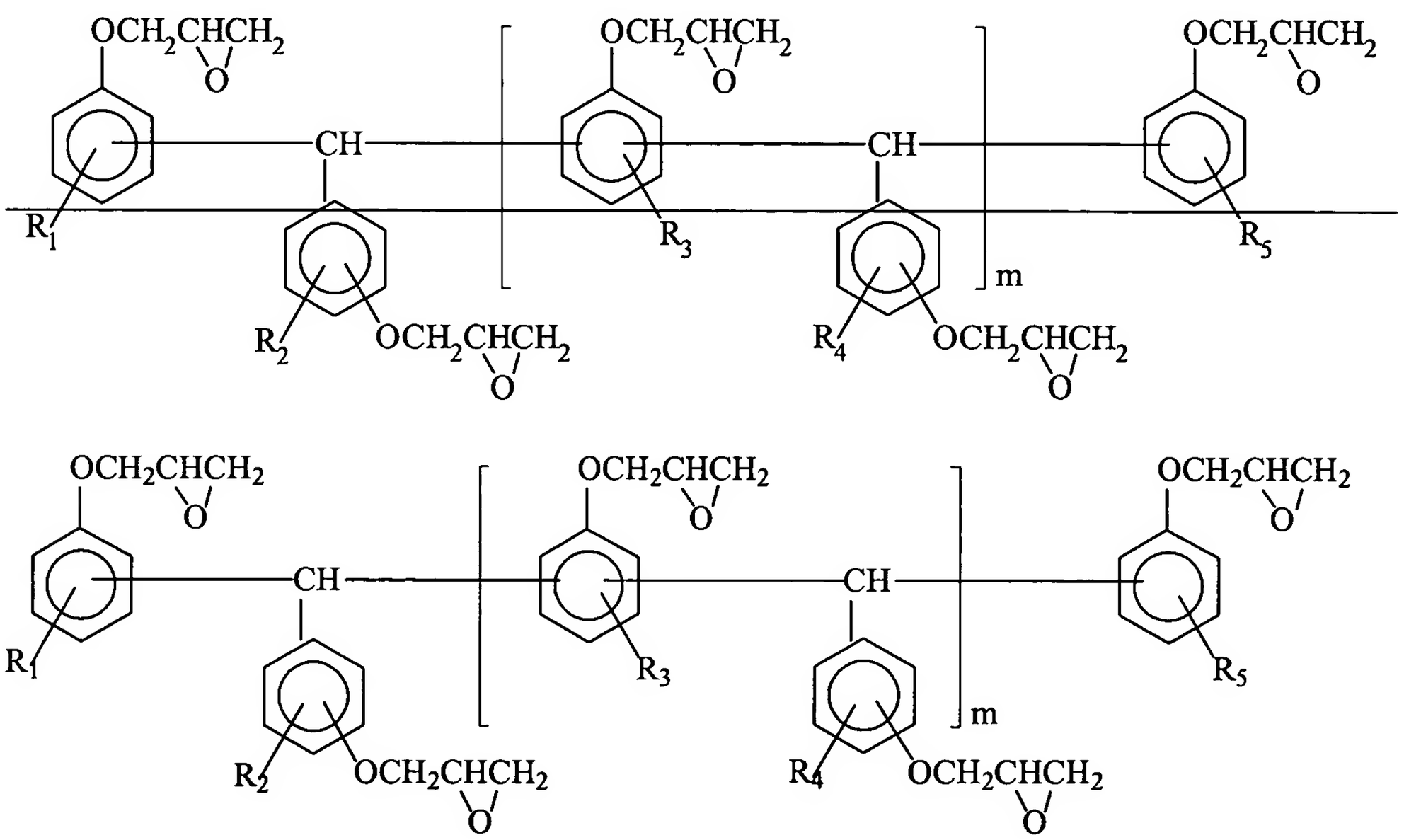
AMENDED CLAIM SET:

1. (currently amended) A process for producing a wafer with a resin layer comprising plural projected electrodes and a cured resin layer formed on a projected electrode mounting side of the wafer, comprising the steps of:

putting, on the projected electrode-mounting side of the wafer, a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):



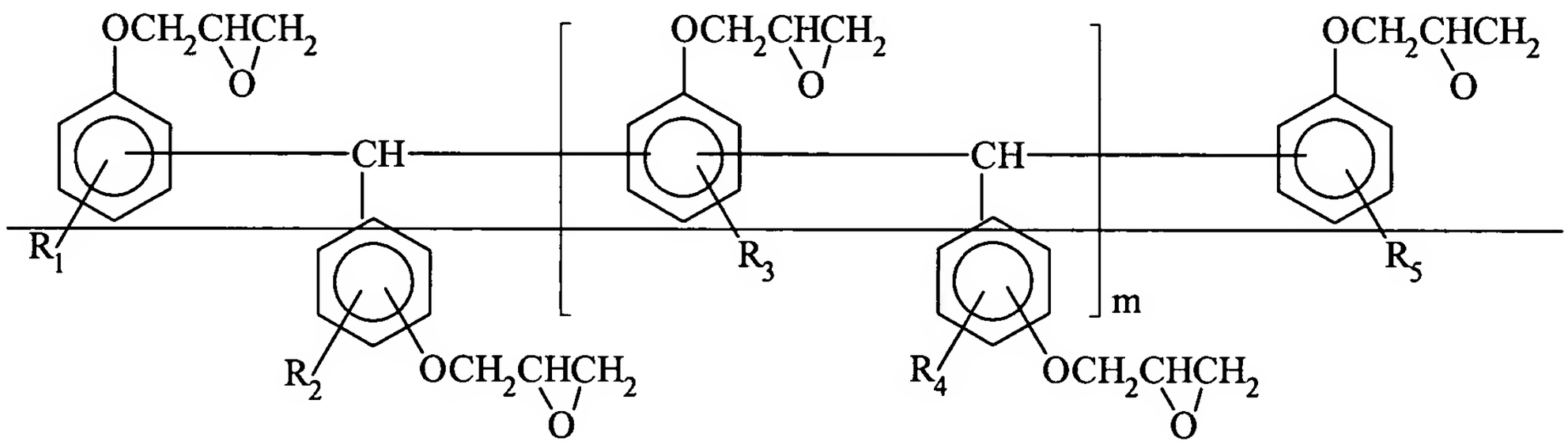
wherein each of R_1 to R_5 is a hydrogen atom and m is 0 or a positive number of 5 or less, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and

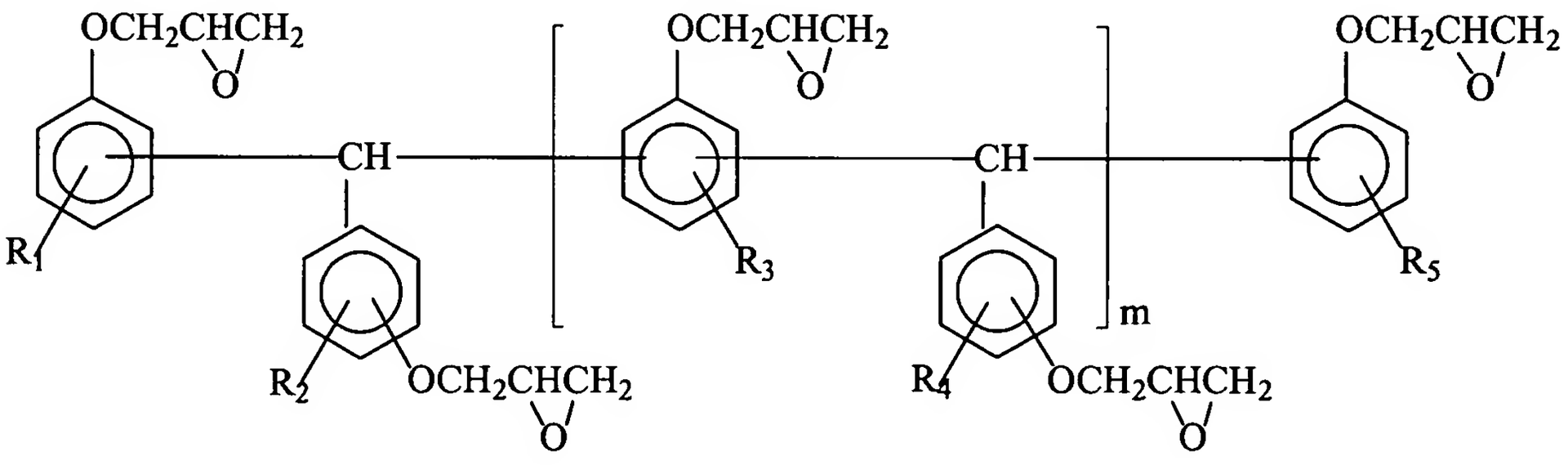
thereafter cooling and solidifying the molten product, and wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and

heating the tablet to be melt-cured, thereby forming the cured resin layer.

2. (currently amended) A process for producing a semiconductor device having substantially no bowing, said semiconductor device comprising an insulating substrate, a semiconductor element mounted on one side of the insulating substrate, and a cured product of an epoxy resin composition, the semiconductor element being incorporated in and sealed by the cured product, comprising the steps of:

putting, on the semiconductor element, a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):



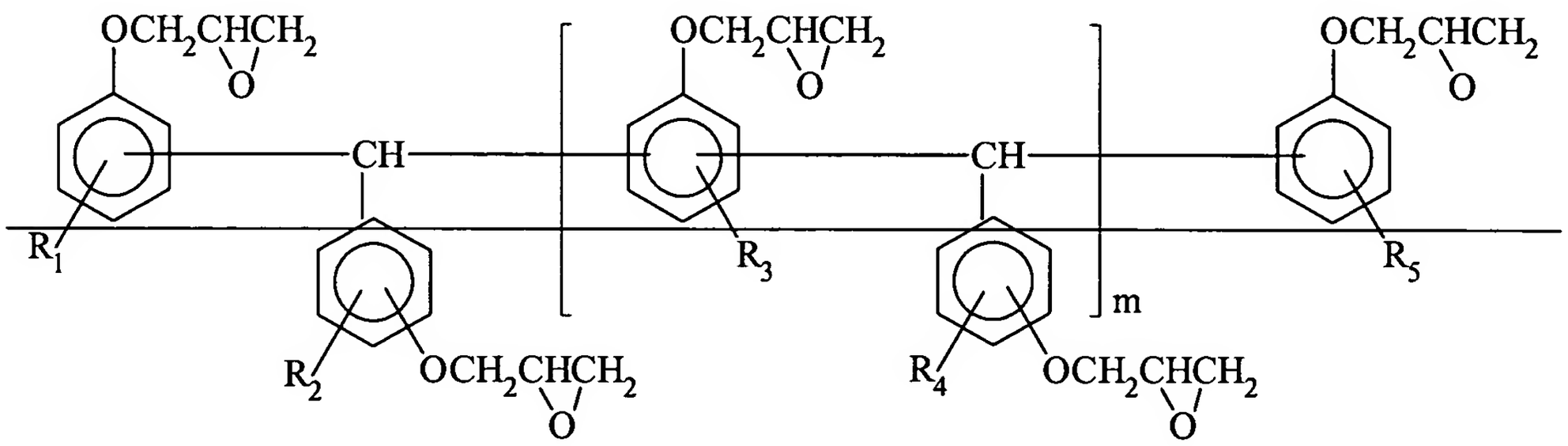


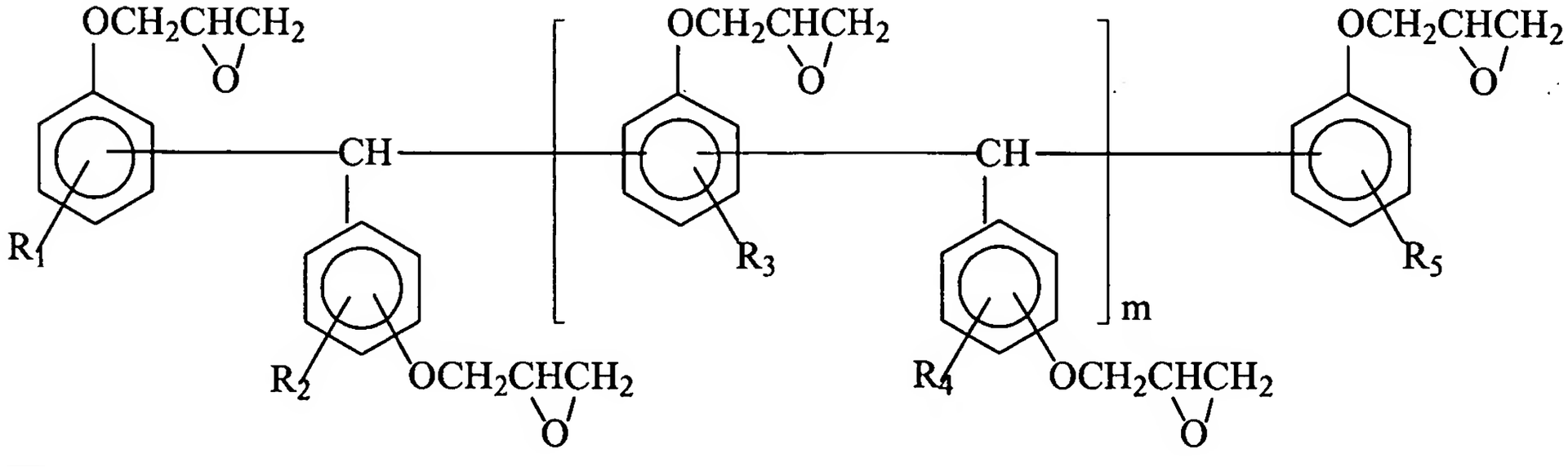
wherein each of R_1 to R_5 is a hydrogen atom and m is 0 or a positive number of 5 or less, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and thereafter cooling and solidifying the molten product, and wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and

heating the tablet to be melt-cured, thereby forming the cured product.

3. (currently amended) A process for producing a semiconductor device having substantially no bowing, said semiconductor device comprising an insulating substrate, a semiconductor element mounted on one side of the insulating substrate via a plural connecting electrodes, and a cured resin layer sealing a void between the insulating substrate anal the semiconductor element, comprising the steps of:

heat-melting a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):





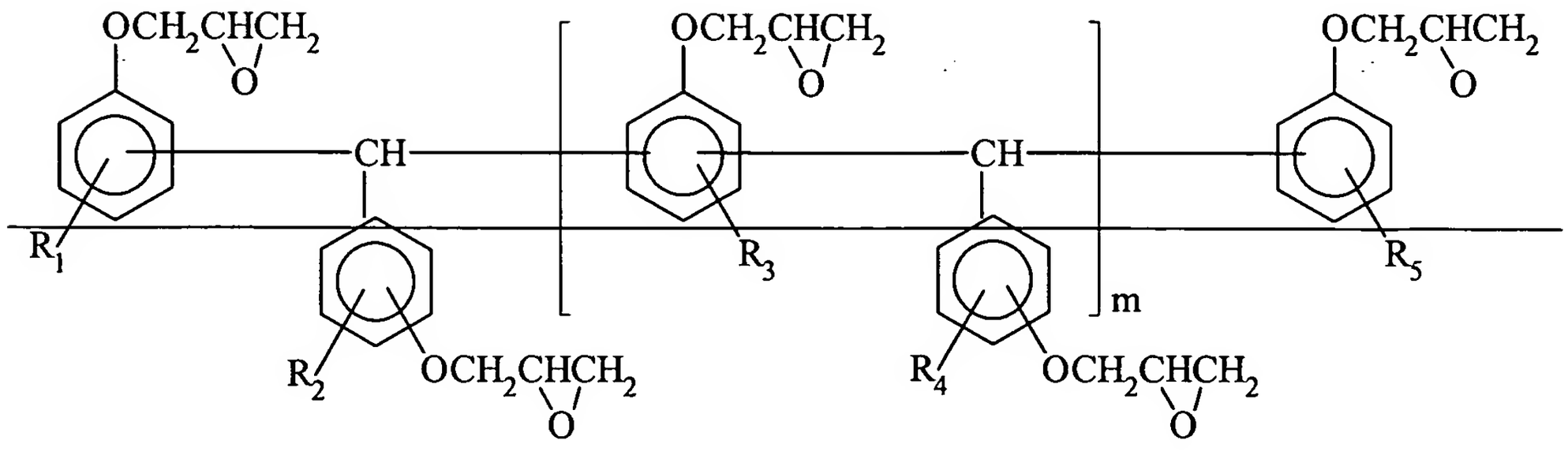
wherein each of R_1 to R_5 is a hydrogen atom and m is 0 or a positive number of 5 or less, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and thereafter cooling and solidifying the molten product, and wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and

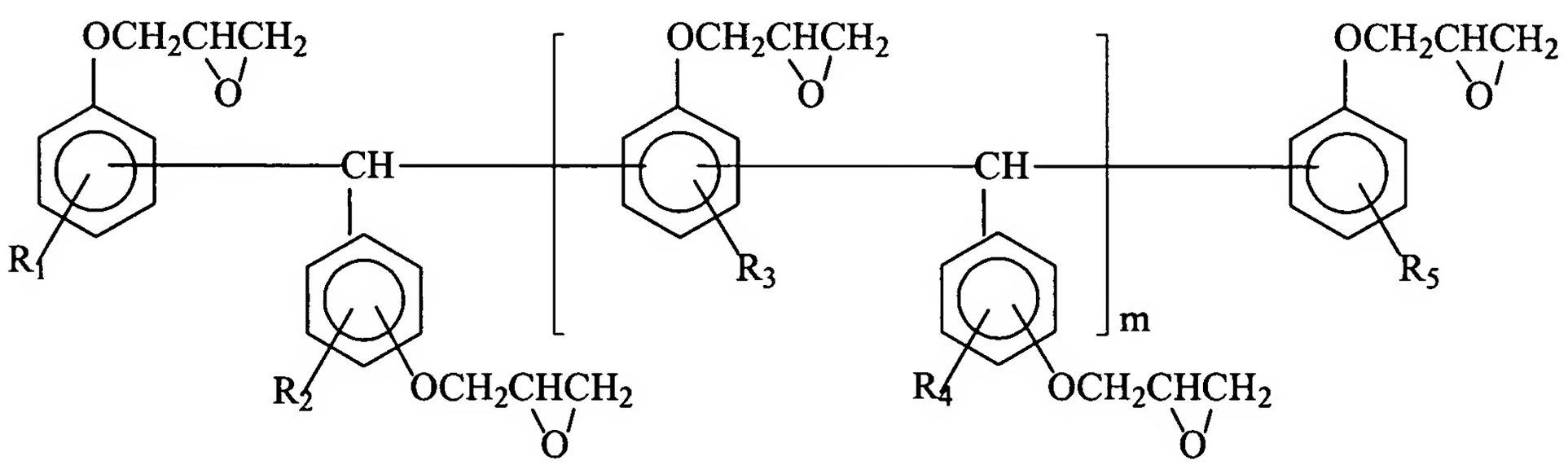
filling the void and curing the tablet, thereby forming the cured resin layer.

4. (cancelled).

5. (currently amended) The process of any one of claims 1 to 3, wherein a compression ratio of the tablet is 98% or more and/or the glass transition temperature of a cured product of the tablet ~~table~~ is 120°C or more.

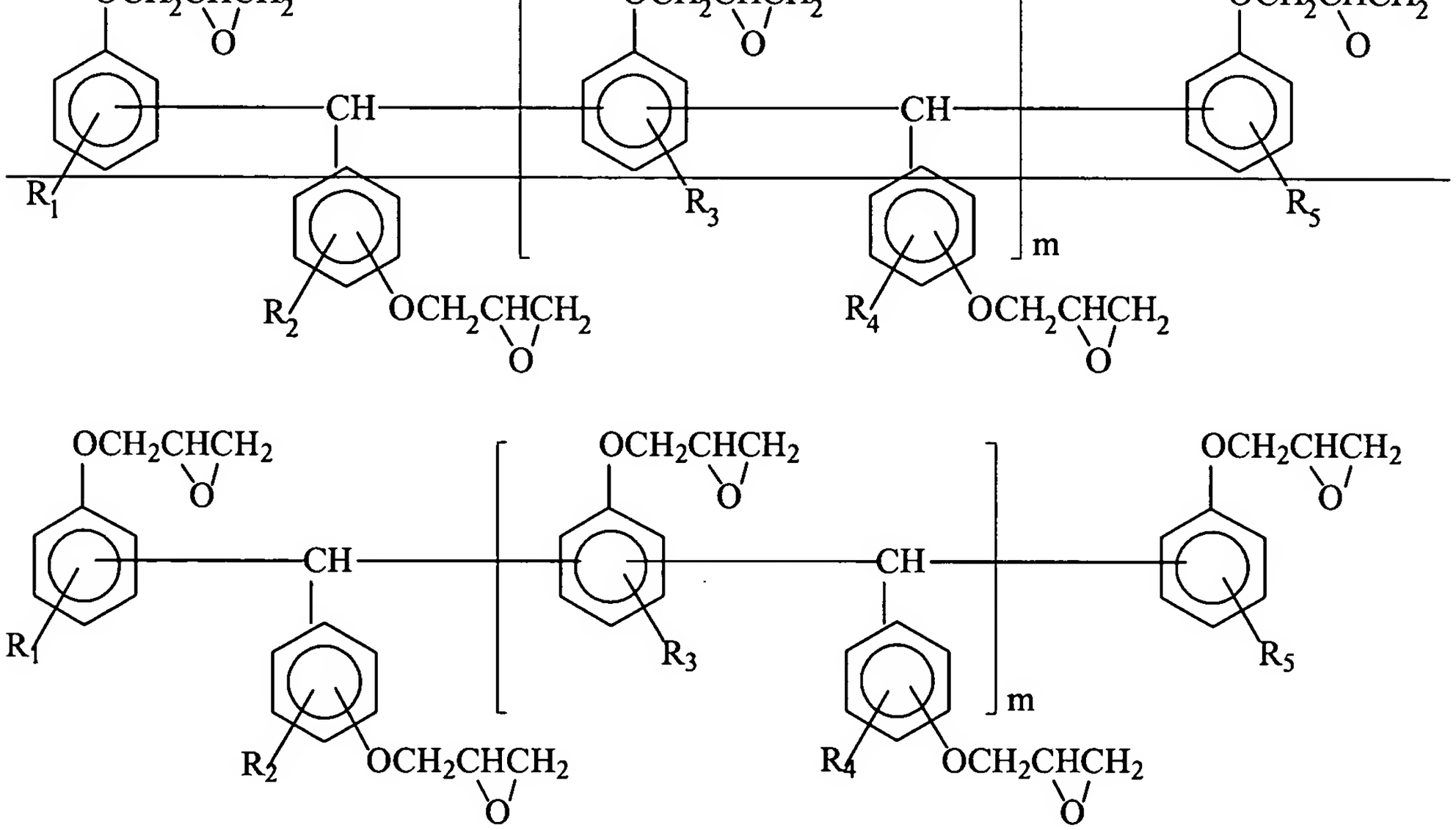
6. (currently amended) A method for preventing generation of bowing of a wafer, said method comprising forming a cured resin layer on a wafer by using a tablet comprising an epoxy resin composition, said epoxy resin composition comprising an epoxy resin represented by the general formula (1):





wherein each of R_1 to R_5 is a hydrogen atom and m is 0 or a positive number of 5 or less and a curing agent, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and thereafter cooling and solidifying the molten product, and wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight.

7. (currently amended) A method for preventing generation of bowing of a semiconductor device, said method comprising sealing semiconductor elements on one side of an insulating substrate by using a tablet comprising an epoxy resin composition, said epoxy resin composition comprising an epoxy resin represented by the general formula (1):



wherein each of R_1 to R_5 is a hydrogen atom and m is 0 or a positive number of 5 or less and a curing agent, wherein said tablet is produced by a process comprising preparing a molten product of said epoxy resin composition in an uncured state and thereafter cooling and solidifying the molten product, and wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight.